Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D
			*** : Required Field**

Supplier Information			
Company Name *	STMicroelectronics	**Response Date ***	2015-12-04
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Flavio Di Francesco	**Representative Title**	AMS Materials Declaration Champion
Representative Phone *	Refer to Supplier Comment section	**Representative Email ***	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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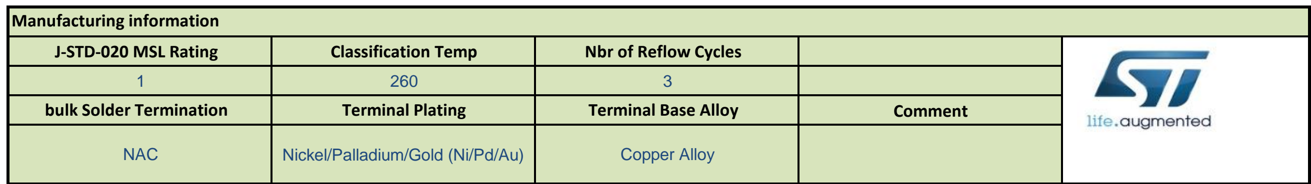
Legal Statement

Supplier Acceptance *	true	**Legal Declaration ***	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	FBE3*A236AAY	A	ZY1A	2015-12-04
	Amount	UoM	Unit type	ST ECOPACK Grade
	23.71	mg	Each	ECOPACK® 3



Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	3X3X0.86	8	gull wing	
Comment	Package: MSOP/TSSOP 8 BODY3.00 PITCH0.65; MD valid for TSB572IYST			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**true**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false

Exemption Id.	**Description**

QueryList : REACH-15th June 2015				
Query				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	FBE3*A236AAY					
Homogeneous Material	**Material Group**	Mass	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or Dies	Other inorganic materials	1.682	mg	supplier	die	Silicon (Si)	7440-21-3		1.640	mg	975030	69184
Die or Dies				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	3567	253
Die or Dies				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	1189	84
Die or Dies				supplier	Passivation	Silicon Nitride	12033-89-5		0.004	mg	2378	169
Die or Dies				supplier	Passivation	Silicon Oxide	7631-86-9		0.015	mg	8918	633
Die or Dies				supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.015	mg	8918	633
Leadframe	Copper & its alloys	9.171	mg	supplier	alloy	Copper (Cu)	7440-50-8		8.647	mg	942863	364775
Leadframe				supplier	alloy	Nickel (Ni)	7440-02-0		0.270	mg	29441	11390
Leadframe				supplier	alloy	Silicon (Si)	7440-21-3		0.058	mg	6324	2447
Leadframe				supplier	alloy	Magnesium (Mg)	7439-95-4		0.013	mg	1418	548
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.177	mg	19300	7467
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.004	mg	436	169
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.002	mg	218	84
Die attach	Other inorganic materials	0.321	mg	supplier	glue	Epoxy resin A	9003-36-5		0.023	mg	71651	970
Die attach				supplier	glue	Epoxy resin B	68475-94-5		0.013	mg	40498	548
Die attach				supplier	glue	Silver(Ag)	7440-22-4		0.246	mg	766355	10378
Die attach				supplier	glue	Lactone	96-48-0		0.013	mg	40498	548
Die attach				supplier	glue	Polyoxypropylenediamine	9046-10-0		0.013	mg	40498	548
Die attach				supplier	glue	2,6-Diglycidyl phenyl allyl ether oligomer	proprietary		0.013	mg	40498	548
Bonding wire	Precious metals	0.068	mg	supplier	wire	Gold (Au)	7440-57-5		0.068	mg	1000000	2869
encapsulation	Other inorganic materials	12.463	mg	#N/A	mold compound	Epoxy Resin	proprietary		1.190	mg	95483	50200
encapsulation				supplier	mold compound	Silica fused (SiO2)	60676-86-0		10.406	mg	834951	438979
encapsulation				supplier	mold compound	Phenol Resin	Trade secret		0.805	mg	64591	33959
encapsulation				supplier	mold compound	Carbon Black	1333-86-4		0.061	mg	4894	2573
encapsulation				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	80	42